L Number	Hits	Search Text	DB	Time stamp
2	165	(((((((((conduct\$3 near5 foil) or ((copper	USPAT;	2004/03/31 12:04
_		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	
) and (insulat\$3 dielectric)) and etch\$3)		
		and (trench recess open\$3 hole groove)) and	1	
		(semiconductor wafer substrate)) and (copper		
		Cu aluminum Al (iron?nickel (iron near3		
		nickel)))) and (PR photoresist resist		
		photo?resist)) and resin) and ((electoless		
		near3 plat\$3) electo?plat\$3 (electro near3		
		plat\$3))		
3	0	(((((((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2004/03/31 12:04
	·	aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	2001,03,31 12.04
) and (insulat\$3 dielectric)) and etch\$3)	IBM TDB	
i l		and (trench recess open\$3 hole groove)) and	12.12.2	
		(semiconductor wafer substrate)) and (copper		
		Cu aluminum Al (iron?nickel (iron near3		-
		nickel)))) and (PR photoresist resist		
		photo?resist)) and resin) and ((electoless		
		near3 plat\$3) electo?plat\$3 (electro near3		
		plat\$3))		
4	12105	(((((conduct\$3 near5 foil) or ((copper	USPAT;	2004/03/31 12:05
•	12105	aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	2004/03/31 12:03
) and (insulat\$3 dielectric)) and (trench	05 10102	
		recess open\$3 hole groove)) and resin		
5	288	(((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2004/03/31 12:05
		aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	2001, 03, 32 12:03
) and (insulat\$3 dielectric)) and (trench	IBM TDB	j
		recess open\$3 hole groove)) and resin		
6	38		USPAT;	2004/03/31 12:06
		trench)	US-PGPUB	
7	34		USPAT;	2004/03/31 12:08
		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	,,
) and (insulat\$3 dielectric)) and (trench		1
		recess open\$3 hole groove)) and resin) and		
		(conductive near3 foil) and (isolat\$3 near5		i l
		trench)		
8	38	((conductive near3 foil) and (isolat\$3 near5	USPAT;	2004/03/31 12:06
		trench)) ((((((conduct\$3 near5 foil) or	US-PGPUB	
		((copper aluminum) near5 (film sheet))) and		
•		pattern\$3) and (insulat\$3 dielectric)) and		
	!	(trench recess open\$3 hole groove)) and		
		resin) and (conductive near3 foil) and		[
		(isolat\$3 near5 trench))		
9	0	(((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2004/03/31 12:08
		aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	
) and (insulat\$3 dielectric)) and (trench	IBM TDB	
		recess open\$3 hole groove)) and resin) and	_	
		(conductive near3 foil) and (isolat\$3 near5		
		trench)		
		1	L	1